

News Release

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Fujifilm to Expand CMP Slurry Production Capacity in the United States

New production capabilities at the Mesa, Arizona, facility will support growing demand for copper interconnects and advanced packaging applications

TOKYO, October 14, 2026 – FUJIFILM Corporation will expand its semiconductor materials business by enhancing production facilities for copper interconnect CMP (Chemical Mechanical Planarization) slurries^{*1} at the FUJIFILM Electronic Materials U.S.A., Inc. production site in Mesa, Arizona. Fujifilm will also establish new production facilities capable of multi-product manufacturing of CMP slurries for diversified semiconductor manufacturing processes, including advanced packaging applications.

The investment, totaling \$18 million USD (approximately ¥3 billion), addresses increasing demand for copper interconnect CMP slurries, and supports long-term growth in advanced logic, advanced memory and advanced packaging applications.

“The advanced semiconductor market has entered a period of significant growth, driven by the rapid expansion of demand related to artificial intelligence,” says Brian O’Donnelly, president & CEO, FUJIFILM Electronic Materials U.S.A., Inc. and corporate vice president, FUJIFILM Corporation. “As global semiconductor demand continues to increase, demand for CMP slurries—an essential material used in advanced semiconductor manufacturing—is also growing.”

In particular, demand for CMP slurry for copper interconnects, a product for which Fujifilm has a leading global market share, is increasing in the advanced logic and memory sectors.

In the United States, major semiconductor manufacturers continue to invest in new and expanded production facilities, resulting in high demand for semiconductor materials. In response to these market conditions, FUJIFILM Electronic Materials U.S.A., Inc will expand its CMP slurry production in Mesa, Arizona. In addition to expanding capacity for copper interconnect CMP slurries used in BEOL^{*2} processes, Fujifilm will establish new production facilities capable of manufacturing a wide range of CMP slurry products for FEOL^{*3}, MOL^{*4} and advanced packaging applications, including hybrid bonding. The new production facilities will serve as a bridge between product development and commercial manufacturing, enabling technologies developed at the Arizona

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The expanded production line is scheduled to begin operations in 2027. Once operational, CMP slurry production capacity at Fujifilm's Mesa facility will further support medium- and long-term growth in demand.

Going forward, Fujifilm will continue to provide a broad portfolio covering nearly all semiconductor manufacturing processes, from leading-edge to legacy nodes.

Leveraging its global manufacturing network across Japan, the United States, Europe and Asia, together with its strong R&D capabilities, Fujifilm will offer one-stop solutions that help address customers' challenges and contribute to the continued development of the semiconductor industry.

About Fujifilm's Semiconductor Materials Business

Fujifilm offers a wide range of materials used throughout the entire semiconductor manufacturing process, from front-end to back-end. These materials include photoresists^{*5}, photolithography-related materials^{*6}, CMP slurries, post-CMP cleaners^{*7}, thin-film materials^{*8}, photosensitive insulating materials such as polyimides^{*9} under the ZEMATES^{™*10} brand, and high-purity process chemicals^{*11}. Fujifilm also provides Wave Control Mosaic^{™*12}, a group of functional materials including color filter materials for image sensors. With an extensive portfolio covering semiconductor manufacturing processes from leading-edge to legacy nodes, Fujifilm maintains a global supply chain with manufacturing and research and development sites in Asia, the United States, and Europe. By providing a one-stop solution to address customer needs, the company contributes to the advancement of the semiconductor industry.

*1 CMP slurry is an abrasive material used to uniformly flatten semiconductor surfaces where wiring and insulating films of varying hardness coexist.

*2 BEOL (Back End of Line): The wiring process in semiconductor manufacturing in which devices such as transistors formed on a wafer are interconnected with metal wiring layers, enabling electrical signal transmission throughout the integrated circuit.

*3 FEOL (Front End of Line): The process of forming semiconductor devices, such as transistors, capacitors, and resistors, on the surface of a silicon wafer.

*4 MOL (Middle of Line): The intermediate interconnection process that connects the terminals of transistors formed during FEOL to the first layer of metal interconnects.

*5 Photosensitive material used to coat a wafer substrate when circuit patterns are drawn using photochemical reactions in the process of semiconductor manufacturing.

*6 Development solutions, cleaners and other materials used in the photolithography process of semiconductor manufacturing.

*7 Cleaners used after polishing with CMP slurry to remove particles, minute metal fragments and organic residues while protecting the metal surface.

*8 Materials for forming low-dielectric insulation films.

*9 A material with strong heat resistance and insulation properties, used for forming semiconductors protective films and rewiring layer.

*10 ZEMATES is a registered trademark or trademark of FUJIFILM Corporation.

*11 High-purity chemicals used in the cleaning and drying processes. The chemicals are employed to remove contaminants during the cleaning and drying stages of semiconductor manufacturing, as well as to eliminate metals and oils during the

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sensors, used in digital cameras and smartphones. WAVE CONTROL MOSAIC is a registered trademark or trademark of FUJIFILM Corporation.

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* Please note that the contents including the product availability, specification, prices and contacts in this website are current as of the date of the press announcement and may be subject to change without prior notice.

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